FEATURES

- Precision 1:4, 400mV LVPECL fanout buffer
- Guaranteed AC performance over temperature and voltage:
 - >5.5GHz f_{MAX} clock
 - <80ps t,/t, times</p>
 - <250ps (V_{IN} ≥ 300mV) t_{pd}
 - <15ps max. skew
- Low jitter performance:
 - <10ps_{pp} total jitter (clock)
 - <1ps_{pms} random jitter (data)
 - <10ps_{pp} deterministic jitter (data)
- Accepts an input signal as low as 100mV
- Unique input termination and V_T pin accepts DC- and AC-coupled differential inputs: LVPECL, LVDS and CML
- 400mV LVPECL compatible outputs
- Power supply 2.5V ±5% and 3.3V ±10%
- -40°C to +85°C temperature range
- Available in 16-pin (3mm × 3mm) MLF® package

APPLICATIONS

- All SONET and All GigE clock distribution
- Fibre Channel clock and data distribution
- Backplane distribution
- Data distribution: OC-48, OC-48+FEC, XAUI
- High-end, low-skew, multiprocessor synchronous clock distribution

100

Precision Edge®

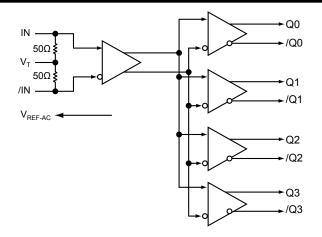
DESCRIPTION

The SY58022U is a 2.5V/3.3V precision, high-speed, fully differential 1:4 LVPECL fanout buffer. Optimized to provide four identical output copies with less than 15ps of skew and less than 10ps_{pp} total jitter, the SY58022U can process clock signals as fast as 5.5GHz.

The differential input includes Micrel's unique, 3-pin input termination architecture interfaces to differential LVPECL, CML, and LVDS signals (AC- or DC-coupled) as small as 100mV without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an on-board output reference voltage ($V_{\text{REF-AC}}$) is provided to bias the V_{T} pin. The outputs are 400mV LVPECL compatible, with extremely fast rise/fall times guaranteed to be less than 80ps.

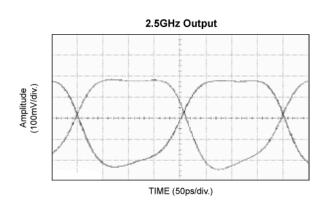
The SY58022U operates from a 2.5V $\pm 5\%$ supply or 3.3V $\pm 10\%$ supply and is guaranteed over the full industrial temperature range (-40° C to $+85^{\circ}$ C). For applications that require greater output swing or CML compatible outputs, consider the SY58021U 1:4 fanout buffer with LVPECL outputs, or the SY58020U 1:4 fanout buffer with 400mV CML outputs. The SY58022U is part of Micrel's high-speed, Precision Edge® product line. All data sheets and support documentation can be found on Micrel's web site at: www. micrel.com.

FUNCTIONAL BLOCK DIAGRAM



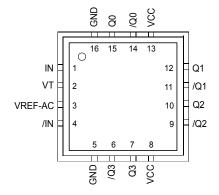
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TYPICAL PERFORMANCE



Rev.: E Amendment: /1 Issue Date: June 2009

PACKAGE/ORDERING INFORMATION



Ordering Information(1)

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58022UMI	MLF-16	Industrial	022U	Sn-Pb
SY58022UMITR(2)	MLF-16	Industrial	022U	Sn-Pb
SY58022UMG	MLF-16	Industrial	022U with Pb-Free bar-line indicator	Pb-Free NiPdAu
SY58022UMGTR ⁽²⁾	MLF-16	Industrial	022U with Pb-Free bar-line indicator	Pb-Free NiPdAu

Notes:

- 1. Contact factory for die availability. Die are guaranteed at $T_A = 25$ °C, DC electricals only.
- 2. Tape and Reel.

16-Pin MLF® (MLF-16)

PIN DESCRIPTION

Pin Number	Pin Name	Pin Function
1, 4	IN, /IN	Differential Input: This input pair receives the signal to be buffered. Each pin is internally terminated with 50Ω to the $V_{\scriptscriptstyle T}$ pin. Note that this input will default to an indeterminate state if left open. See "Input Interface Applications" section.
2	VT	Input Termination Center-Tap: Each input terminates to this pin. The V_T pin provides a center-tap for each input (IN, /IN) to the termination network for maximum interface flexibility. See "Input Interface Applications" section.
3	VREF-AC	Reference Output Voltage: This output biases to $V_{\rm CC}$ –1.2V. It is used when AC-coupling to differential inputs. Connect $V_{\rm REF-AC}$ directly to the $V_{\rm T}$ pin. Bypass with 0.01 μ F low ESR capacitor to $V_{\rm CC}$. See "Input Interface Applications" section.
8, 13	VCC	Positive Power Supply: Bypass with $0.1\mu F//0.01\mu F$ low ESR capacitors as close to the pins as possible. A $0.01\mu F$ capacitor should be as close to the V_{cc} pin as possible.
5, 16	GND, Exposed Pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pin.
14, 15 11, 12 9, 10 6, 7	/Q0, Q0, /Q1, Q1, /Q2, Q2, /Q3, Q3,	LVPECL Differential Output Pairs: Differential buffered output copy of the input signal. The output swing is typically 400mV. Proper termination is 50Ω to V_{cc} –2V at the receiving end. Unused output pairs may be left floating with no impact on jitter or skew. See "LVPECL Output Termination" section.

Absolute Maximum Ratings(1)

Power Supply Voltage (V _{CC})0.5V to +4.0V	V
Input Voltage (V _{IN})–0.5V to V _C	cc
Output Current (I _{OUT})	
Continuous	ıA
Surge	ıA
V _τ Current Source or sink current on V _τ pin±100m	ıΑ
Input Current	. ^
Source or sink current on (IN, /IN)±50m. V _{REF} Current	Α
Source or sink current on V _{REF-AC} , Note 4 ±1.5m.	ıA
Soldering, (20 sec.)	С
Storage Temperature Range (T _{STORE}) –65 to +150°C	

Operating Ratings⁽²⁾

Power Supply Voltage (V _{cc}) +2.3	75V to +3.60V
Operating Temperature Range (T _A)	40°C to +85°C
Package Thermal Resistance	
$MLF^{\otimes}\left(\Theta_{LA}\right)$	
Still-Air.	60°C/W
500lpfm	54°C/W
MLF® (θ _{JB})	
(Junction-to-Board Resistance), Note 3	33°C/W

DC ELECTRICAL CHARACTERISTICS(Note 5)

 $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$

Symbol	Parameter	Condition	Min	Тур	Мах	Units
V _{cc}	Power Supply Voltage	V _{CC} = 2.5V V _{CC} = 3.3V	2.375 3.0	2.5 3.3	2.625 3.60	V
I _{cc}	Power Supply Current	No load, V _{cc} = max		125	160	mA
V _{IH}	Input HIGH Voltage	IN, /IN, Note 6	V _{cc} -1.6		V _{cc}	V
V _{IL}	Input LOW Voltage	IN, /IN	0		V _{IH} -0.1	V
V _{IN}	Input Voltage Swing	IN, /IN; See Figure 1a	0.1		3.6	V
V _{DIFF_IN}	Differential Input Voltage	IN, /IN; See Figure 1b	0.2		3.4	V
R _{IN}	IN-to-V _⊤ Resistance		40	50	60	Ω
V _{REF-AC}	Output Reference Voltage		V _{cc} -1.3	V _{cc} -1.2	V _{cc} -1.1	V
V_{TIN}	IN-to-V _⊤ Voltage				1.28	V

LVPECL DC ELECTRICAL CHARACTERISTICS(Note 5)

 V_{cc} = 3.3V ±10% or V_{cc} = 2.5 ±5%; R_{I} = 50 Ω to V_{cc} -2V; T_{A} = -40°C to 85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{OH}	Output HIGH Voltage		V _{cc} -1.145	V _{cc} -1.020	V _{cc} -0.895	V
V _{OL}	Output LOW Voltage		V _{cc} -1.545	V _{cc} -1.420	V _{cc} -1.295	V
V _{out}	Output Differential Swing	see Figure 1a	150	400	650	mV
V _{DIFF_OUT}	Differential Output Swing	see Figure 1b	300	800	1300	mV

Notes:

- Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to ABSOLUTE MAXIMUM RATINGS conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Thermal performance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB.
- 4. Due to the limited drive capability, use for input of the same package only.
- 5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- 6. V_{IH}(min.) not lower than 1.2V.

AC ELECTRICAL CHARACTERISTICS

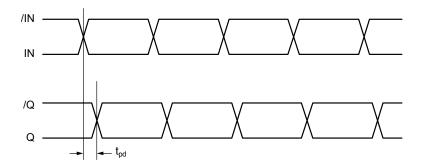
 V_{cc} = 2.5V ±5% or 3.3V ±10%; R_L = 50 Ω to V_{cc} -2V; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Paramete	r	Condition		Min	Тур	Max	Units
f _{MAX}	Maximum Operating Frequency		V _{OUT} ≥ 200mV	Clock	5.5			GHz
				NRZ Data		10		Gbps
t _{pd}	Propagation	on Delay			130	200	280	ps
t _{CHAN}	Channel-to	o-Channel Skew	Note 7			4	15	ps
t _{skew}	Part-to-Pa	rt Skew	Note 8				50	ps
t _{JITTER}	Clock	Cycle-to-Cycle Jitter	Note 9				1	ps _{RMS}
		Total Jitter	Note 10				10	ps _{PP}
	Data	Random Jitter	Note 11	2.5Gbps - 3.2Gbps			1	ps _{RMS}
		Deterministic Jitter	Note 12	2.5Gbps - 3.2Gbps			10	ps _{PP}
t_r , t_f	Output Ris	se/Fall Time 20% to 80%	At full swing		20	50	80	ps

Notes:

- 7. Skew is measured between outputs of the same bank under identical transitions.
- 8. Skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- 9. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, T_n-T_{n-1} where T is the time between rising edges of the output signal.
- 10. Total jitter definition: with an ideal clock input of frequency ≤ f_{MAX}, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.
- 11. Random jitter is measured with a K28.7 comma detect character pattern, measured at 2.5Gbps/3.2Gbps.
- 12. Deterministic jitter is measured at 2.5Gbps/3.2Gbps with both K28.5 and 2²³–1 PRBS pattern.

TIMING DIAGRAM



SINGLE-ENDED AND DIFFERENTIAL SWINGS

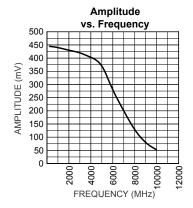


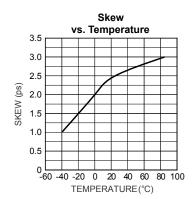
Figure 1a. Single-Ended Swing

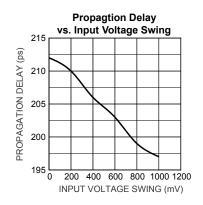
Figure 1b. Differential Swing

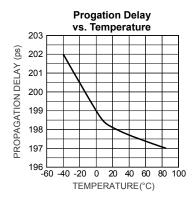
TYPICAL OPERATING CHARACTERISTICS

 $\rm V_{\rm CC}$ = 3.3V, $\rm V_{\rm EE}$ = 0V, $\rm V_{\rm IN}$ = 100mV, $\rm T_{\rm A}$ = 25°C, unless otherwise stated.



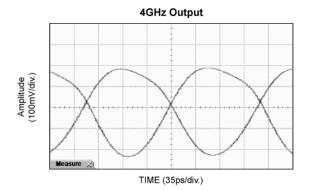


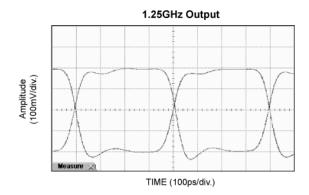


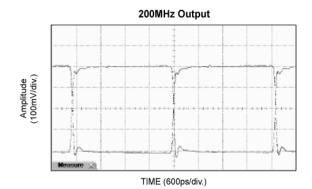


FUNCTIONAL CHARACTERISTICS

 $\rm V_{CC}$ = 3.3V, $\rm V_{EE}$ = 0V, $\rm V_{IN}$ = 100mV, $\rm T_A$ = 25°C, unless otherwise stated.







INPUT STAGE

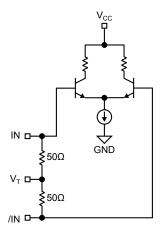


Figure 2. Simplified Differential Input Buffer

INPUT INTERFACE APPLICATIONS

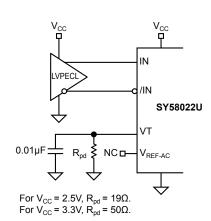


Figure 3a. DC-Coupled LVPECL Input Interface

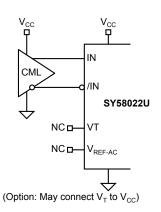
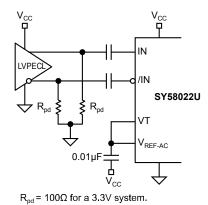


Figure 3d. AC-Coupled CML Input Interface



 R_{pd}^{pd} = 50 Ω for a 2.5V system.

Figure 3b. AC-Coupled LVPECL Input Interface

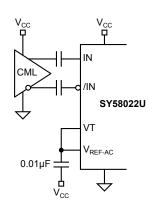


Figure 3e. CML Input Interface

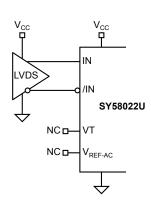


Figure 3c. LVDS Input Interface

OUTPUT TERMINATION RECOMMENDATIONS

LVPECL outputs have very low output impedance (open emitter), and small signal swing which results in low EMI (electro-magnetic interference). The LVPECL is ideal for driving 50Ω - and 100Ω -controlled impedance transmission lines. In addition, LVPECL is compatible for driving standard

Figure 4. Parallel Termination-Thevenin Equivalent

Notes:

- 1. For +2.5V systems: R1 = 250Ω , R2 = 62.5Ω .
- 2. For +3.3V systems: R1 = 130Ω , R2 = 83Ω .

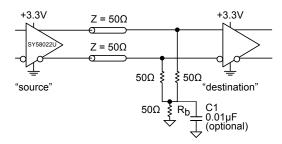


Figure 5. Three-Resistor "Y-Termination"

Notes:

- 1. Power-saving alternative to Thevenin termination.
- 2. Place termination resistors as close to destination inputs as possible.
- 3. R_b resistor sets the DC bias voltage, equal to V_T For +2.5V systems R_b = 19 Ω .
- For +3.3V systems $R_b = 46\Omega$ to 50Ω .
- 4. C1 is an optional bypass capacitor intended to compensate for any $t/t_{\!_{\rm f}}$ mismatches.

PECL inputs since PECL inputs require only 100mV input swing. Further, there are several techniques in terminating the LVPECL outputs, as shown in Figure 4 through 6.

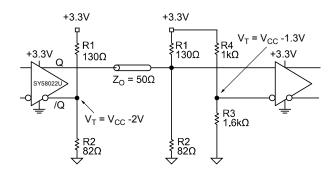


Figure 6. Terminating Unused I/O

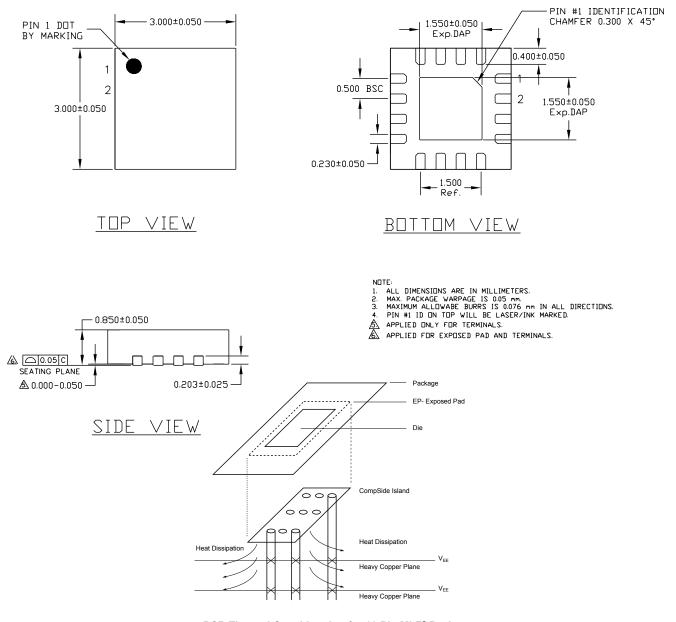
Notes:

- 1. Unused output (/Q) must be terminated to balance the output.
- 2. For +2.5V systems: R1 = 250 Ω , R2 = 62.5 Ω , R3 = 1.25k Ω , R4 = 1.2k Ω .
 - For +3.3V systems: R1 = 130Ω , R2 = 82Ω , R3 = $1k\Omega$, R4 = $1.6k\Omega$.
- 3. Unused output pairs (Q and /Q) may be left floating.

RELATED MICREL PRODUCTS AND SUPPORT DOCUMENTATION

Part Number	Function	Data Sheet Link
SY58020U	6GHz, 1:4 CML Fanout Buffer/Translator Internal I/O Termination	http://www.micrel.com/product-info/prod/ucts/sy58020u.shtml
SY58021U	4GHz, 1:4 LVPECL Fanout Buffer/Translator with Internal Termination	http://www.micrel.com/product-info/products/sy58021u.shtml
SY58022U	5.5GHz, 1:4 Fanout Buffer/Translator w/400mV LVPECL Outputs and Internal Input Termination	http://www.micrel.com/product-info/products/sy58022u.shtml
	16-MLF® Manufacturing Guidelines Exposed Pad Application Note	www.amkor.com/products/notes_papers/MLF_AppNote_0902.pdf
M-0317	HBW Solutions	http://www.micrel.com/product-info/as/solutions.shtml

16-PIN MicroLeadFrame® (MLF-16)



PCB Thermal Consideration for 16-Pin MLF® Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

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